

NCCAUS

Junction Technologies User Group Meeting

www.avsgroups.org

Topic: Updates on New Technologies

Date: July 12, 2019

Time: 1:00 – 5:00 p.m.

Location: EAG Laboratories
810 Kifer Road
Sunnyvale, CA

FREE TO ATTEND—Just Show Up!

SPONSORED BY:

[Axcelis](#)

[Sumitomo Heavy Industries Ion Technology](#)

[UC Components Inc.](#)

Co-Chairs:

Susan Felch, Susan Felch Consulting, sfelch@sbcglobal.net

John Borland, JOB Technologies, JohnOBorland@aol.com

Michael Current, Currentsci@aol.com

AGENDA:

1:00-1:15 p.m. Sue Felch, Susan Felch Consulting Introduction and IIT2020 Announcement

1:15-1:45 p.m. “Comprehensive Characterization of B⁺ Implanted Si after Rapid Thermal Annealing”, Woo Sik Yoo, WaferMasters

1:45-2:30 p.m. “Review of Applications of Defect Photoluminescence Imaging (DPLI) during IC Processing”, John Byrnes, Semilab

2:30-2:45 p.m. Break/Refreshments

2:45-3:30 p.m. “Aspects of Highly-Channeled MeV Dopant Implants in Si(100): Profiles & Defects”, Michael Current, Current Scientific

3:30-4:00 p.m. “Novel Approach to Remove Films at Room Temperature Isotropically & Atomically with Rapid Thermal Pulse Sequences”, Y.S. Kim, Lam Research

4:00-4:30 p.m. “Expand Laser Annealing for Low Thermal Budget Applications”, Shaoyin Chen, Ultratech/Veeco

4:30 p.m. Closing remarks

All presentations will be requested to be posted on the JTG Proceedings webpage approximately 1-2 weeks following the meeting.

➤ *If you would like to sponsor a JTG meetings, please contact Susan Felch, sfelch@sbcglobal.net*

If you would like to sponsor a future User Group meeting please check out the new "[NCCAUS Sponsorship](#)" opportunities.